



IPEC 676 Automated CMP Tool

The IPEC 676 automated CMP system is capable of throughput of 40 or more wafers per hour and offers one of the industry's smallest footprints. The 676 can be used to polish either oxide or metal layers, allowing customers to reduce the number of different CMP systems in a wafer fabrication facility. The 676 is designed to improve yields by use of an orbital polishing motion rather than conventional rotational CMP techniques to enable higher levels of reliability and ease of use.



Standard Features Include:

- Four wafer planarizers
- Three cassette tilter load/unload station
- Advanced pad motion control
- High speed polish drive (0-600 RPM)
- Closed loop delta P control
- Endpoint detection system
- Stainless steel polish bell
- Dual pad conditioning systems
- Upgraded 500MHz Pentium

About Axis Technology

Axis Technology is the industry expert in providing material processing and CMP foundry and wafer grinding services, process tools, and custom configured upgrades that are designed to meet your process and production requirements. We deliver leading-edge CMP, wafer thinning and wafer polishing solutions for semiconductor, MEMS and substrate applications.

Axis Technology sets the standard for creating enabling technologies for field proven production and legacy process equipment.

Customer support services include tool upgrades, spare parts, and field service support for a range of CMP and wafer grinding tools, including installed legacy tools.

Performance Guarantee

Axis Technology is committed to customer satisfaction. While we aggressively pursue the cost and performance goals of our clients, we never compromise on quality or technical performance.

Contact Axis Technology or your local Axis Technology Sales Representative to discuss how Axis can help you get the most from your equipment investment.

Facilities

- Dimensions:
 - Width: 82"
 - Depth: 69"
 - Height: 102"
- Electrical, 120/208 VAC WYE
3 Phase, 60 Hz, 60 Amps Max.
- DI Water: 50psi / 5gpm